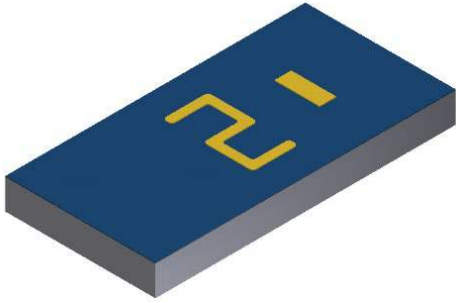


**Surface Mount Attenuator  
10 Watts, 2dB**



The XRA10AA2SES is a high performance Alumina (Al<sub>2</sub>O<sub>3</sub>) chip attenuator intended as a cost competitive alternative to Beryllium Oxide (BeO). It is designed particularly for LTE and 5G wireless communication frequency bands. The high power handling makes the part ideal for inter-stage matching, directional couplers, and for use in isolators. The attenuator is also RoHS compliant!

**General Specifications**

**Features:**

- RoHS Compliant
- 10 Watts
- Low Cost
- DC – 6.0GHz
- Al<sub>2</sub>O<sub>3</sub> Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

<b>Resistive Element</b>	Thick film
<b>Substrate</b>	Al <sub>2</sub> O <sub>3</sub> Ceramic
<b>Terminal Finish</b>	Matte Tin over Nickel Barrier
<b>Operating Temperature</b>	-55 to +150°C (see de rating chart)

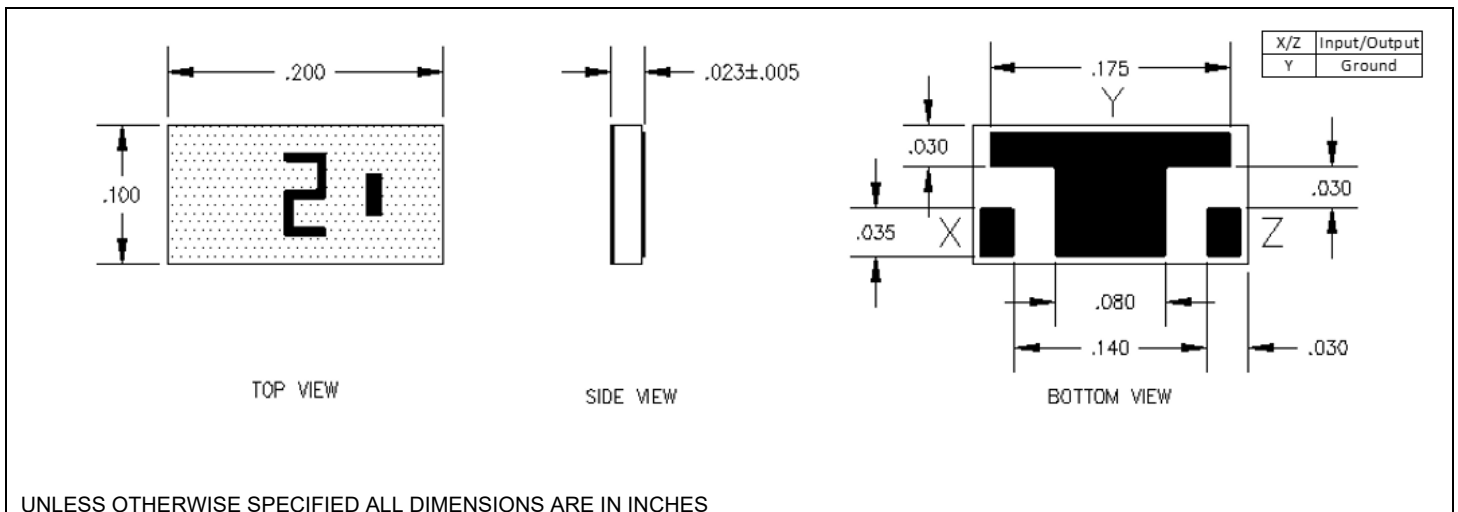
Tolerance is ±0.010", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. **All dimensions in inches.**

**Electrical Specifications**

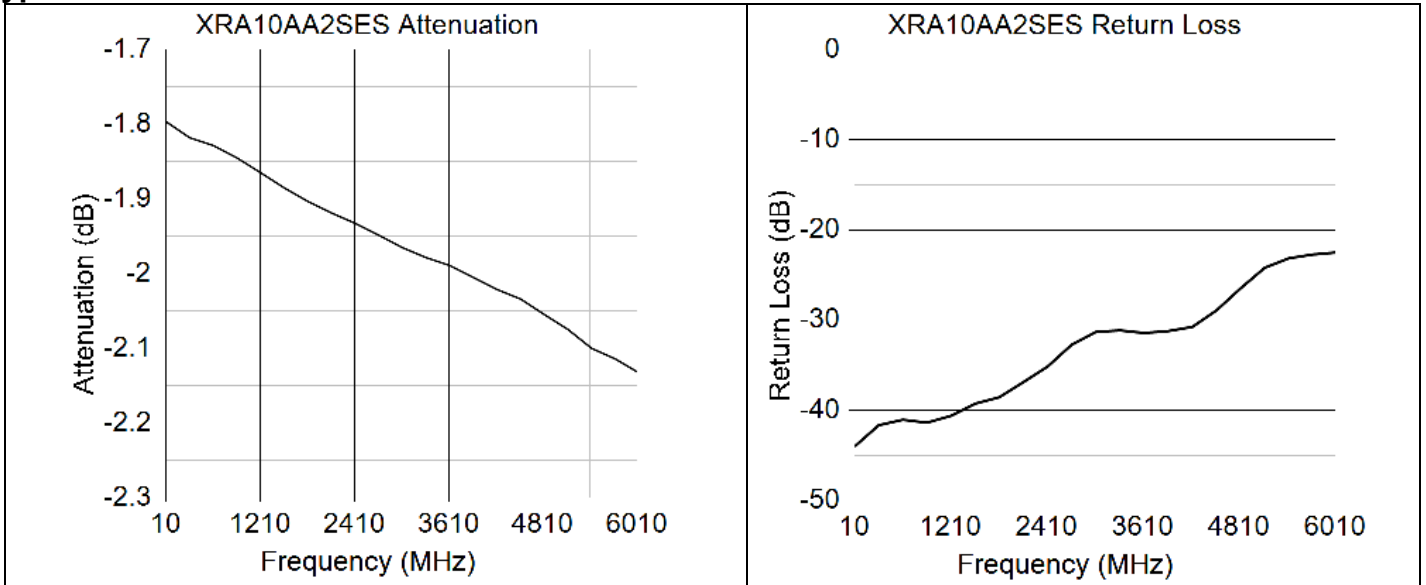
<b>Attenuation Value:</b>	2.0 ± 0.3 dB
<b>Power:</b>	10 Watts
<b>Frequency Range:</b>	DC – 6.0GHz
<b>Input Return Loss:</b>	20dB

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change.**

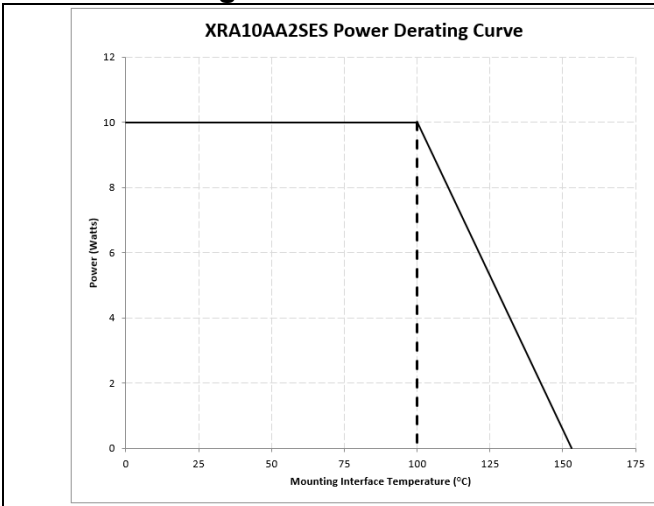
**Outline Drawing**



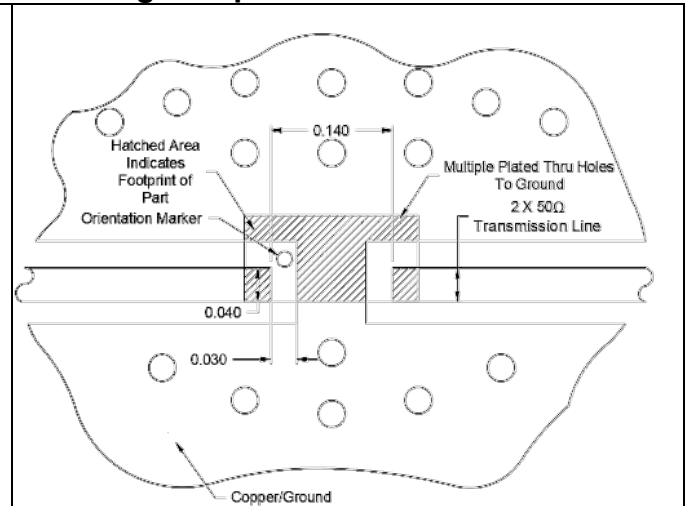
**Typical Performance**



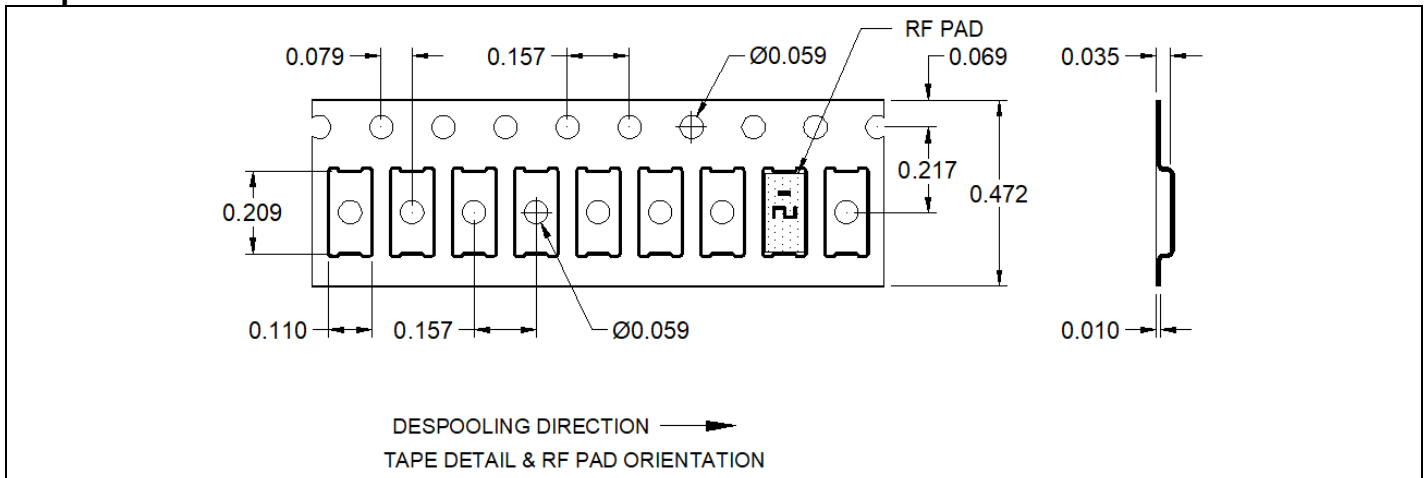
**Power De-Rating:**



**Mounting Footprint:**



**Tape and reel information:**



**Mounting Procedure**

**MOUNTING PROCEDURE**

1. DRILL THERMAL VIAS THROUGH PCB AND FILL WITH SOLDER, SUCH AS Sn96.
2. SOLDER PART IN PLACE USING Sn96 TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON (260°C).
3. TO ENSURE GOOD THERMAL CONNECTIVITY TO HEAT SINK, DRILL AND TAP HEATSINK AND MOUNT PCB BOARD TO HEATSINK USING SCREWS.

**Contact us:**  
[rf&s\\_support@ttm.com](mailto:rf&s_support@ttm.com)